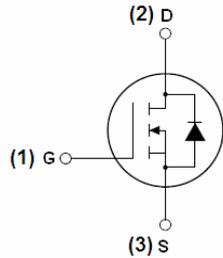
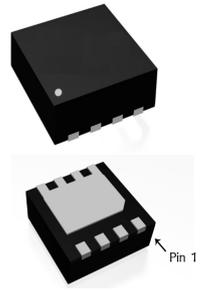


## Description

<p><b>General Features</b></p> <ul style="list-style-type: none"> <li> <table border="1" style="width: 100%; border-collapse: collapse; text-align: center;"> <tr> <th><math>V_{DSS}</math></th> <th><math>R_{DS(ON)}</math> @10V(Typ)</th> <th><math>R_{DS(ON)}</math> @4.5V(Typ)</th> <th><math>I_D</math></th> </tr> <tr> <td>30V</td> <td>4.2m<math>\Omega</math></td> <td>7.1m<math>\Omega</math></td> <td>48A</td> </tr> </table> </li> <li>Advanced Trench Technology</li> <li>Provide Excellent <math>R_{DS(ON)}</math> and Low Gate Charge</li> <li>RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>Load Switch</li> <li>PWM Application</li> <li>Power management</li> </ul>	$V_{DSS}$	$R_{DS(ON)}$ @10V(Typ)	$R_{DS(ON)}$ @4.5V(Typ)	$I_D$	30V	4.2m $\Omega$	7.1m $\Omega$	48A	<div style="text-align: center;">  <p><b>Schematic diagram</b></p> </div> <div style="display: flex; justify-content: space-around; align-items: center; margin-top: 20px;"> <div style="text-align: center;">  <p><b>Marking and pin assignment</b></p> </div> <div style="text-align: center;">  <p><b>DFN3*3-8L</b></p> </div> </div>
$V_{DSS}$	$R_{DS(ON)}$ @10V(Typ)	$R_{DS(ON)}$ @4.5V(Typ)	$I_D$						
30V	4.2m $\Omega$	7.1m $\Omega$	48A						

## Ordering Information

Part Number	Marking	Case	Packaging
G48N03D3	G48N03	DFN3*3-8L	3000pcs/Reel

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	±20	V
$I_D$	Continuous Drain Current	T <sub>C</sub> = 25°C	48
		T <sub>C</sub> = 100°C	30
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	192	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	60	mJ
$P_D$	Power Dissipation	T <sub>C</sub> = 25°C	50
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.5	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +175	°C

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	1.55	2.4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10V, I_D=20A$	-	4.2	4.5	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	7.1	8	
$g_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=15A$	-	28	-	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V,$ $f=1.0MHz$	-	1950	-	pF
$C_{oss}$	Output Capacitance		-	320	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	240	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=25V, I_D=20A,$ $V_{GS}=10V$	-	42	-	nC
$Q_{gs}$	Gate-Source Charge		-	4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	14	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15V,$ $R_I=0.75\Omega, R_{GEN}=3\Omega,$ $V_{GS}=10V$	-	13	-	ns
$t_r$	Turn-on Rise Time		-	36	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	43	-	ns
$t_f$	Turn-off Fall Time		-	16	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	48	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	192	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=20A$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$	-	16	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	5	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, R_G=25\Omega$

Typical Performance Characteristics

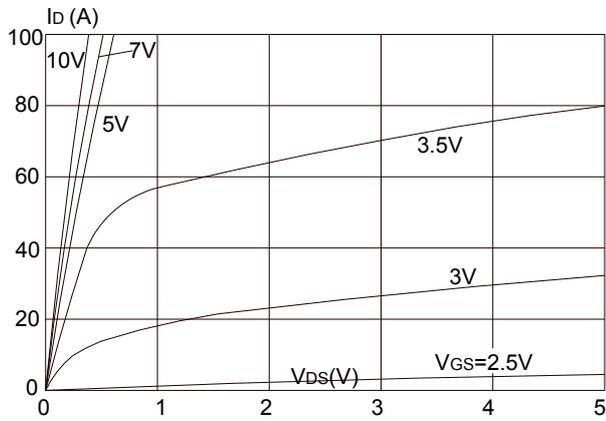


Figure 1: Output Characteristics

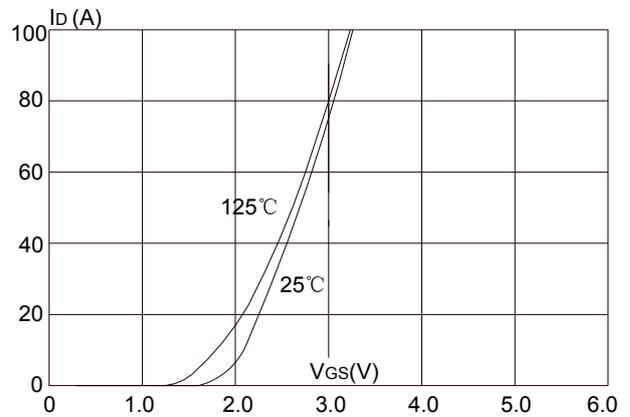


Figure 2: Typical Transfer Characteristics

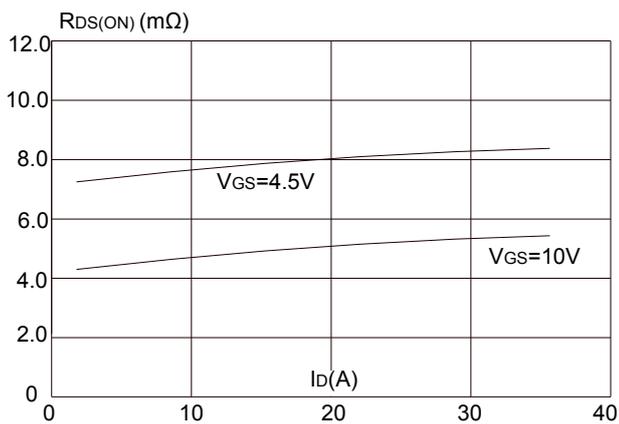


Figure 3: On-resistance vs. Drain Current

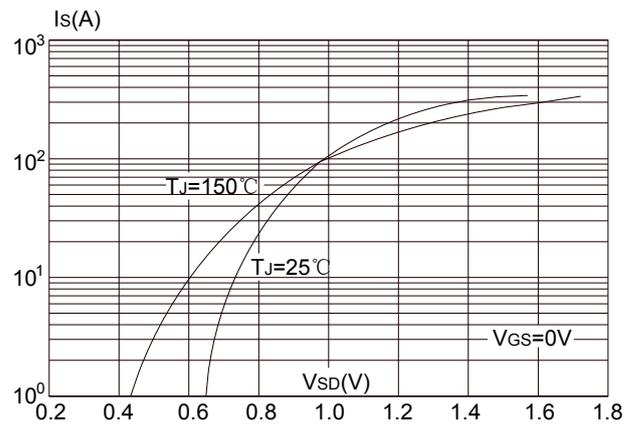


Figure 4: Body Diode Characteristics

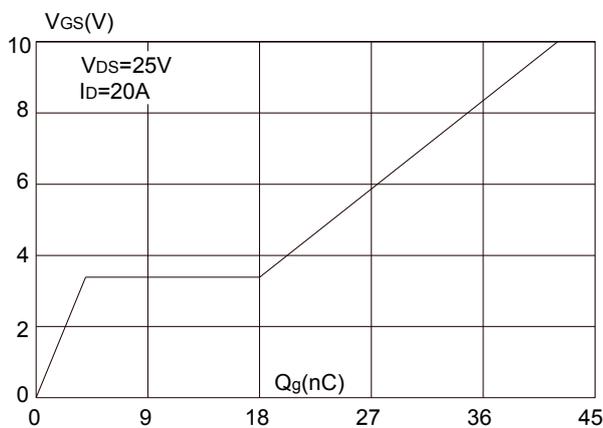


Figure 5: Gate Charge Characteristics

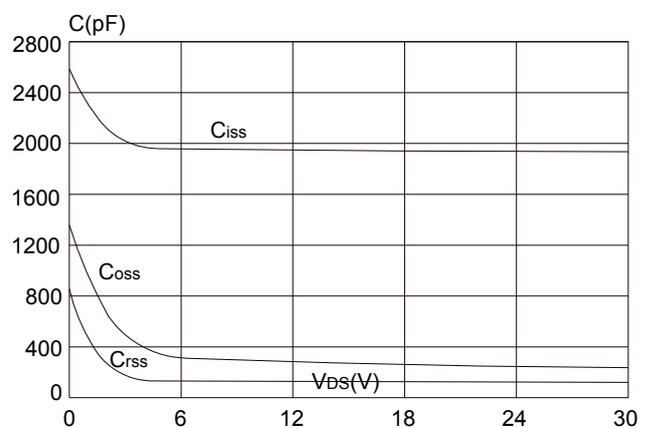
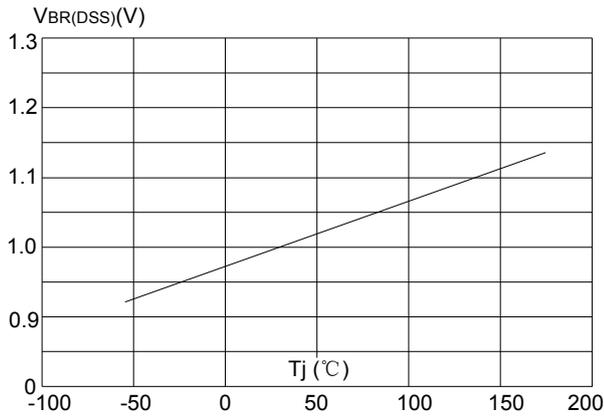
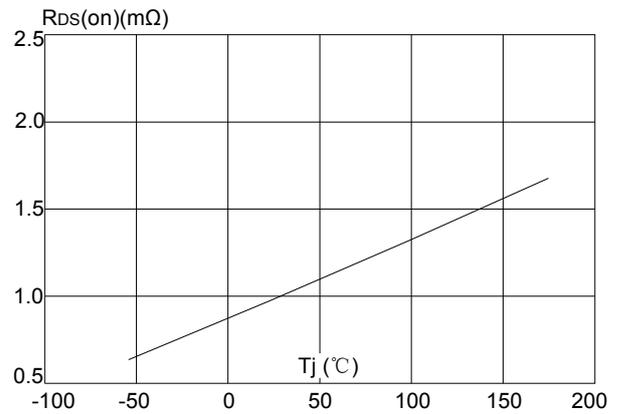


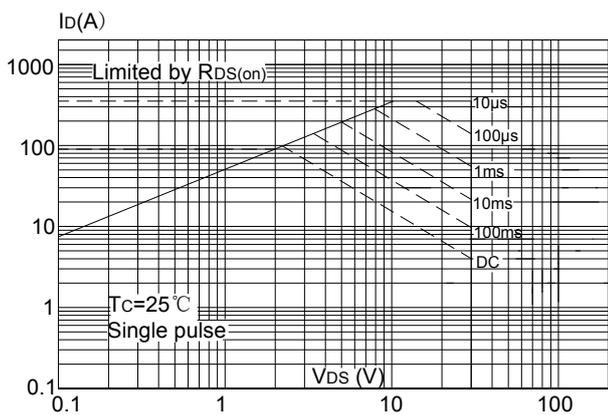
Figure 6: Capacitance Characteristics



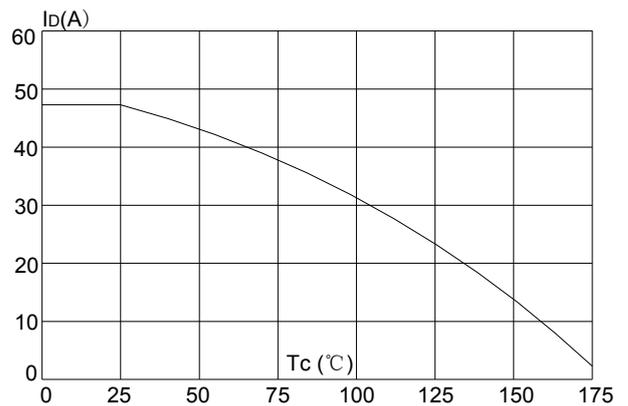
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



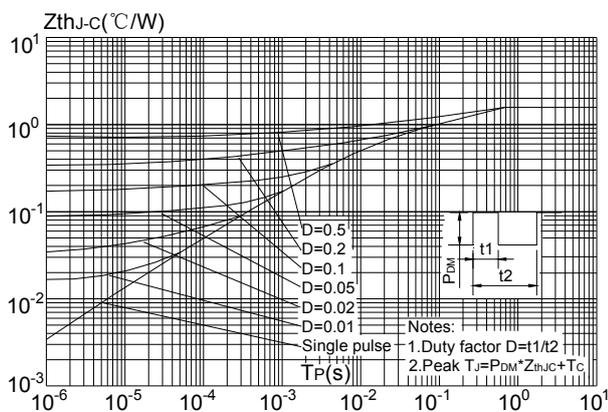
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)

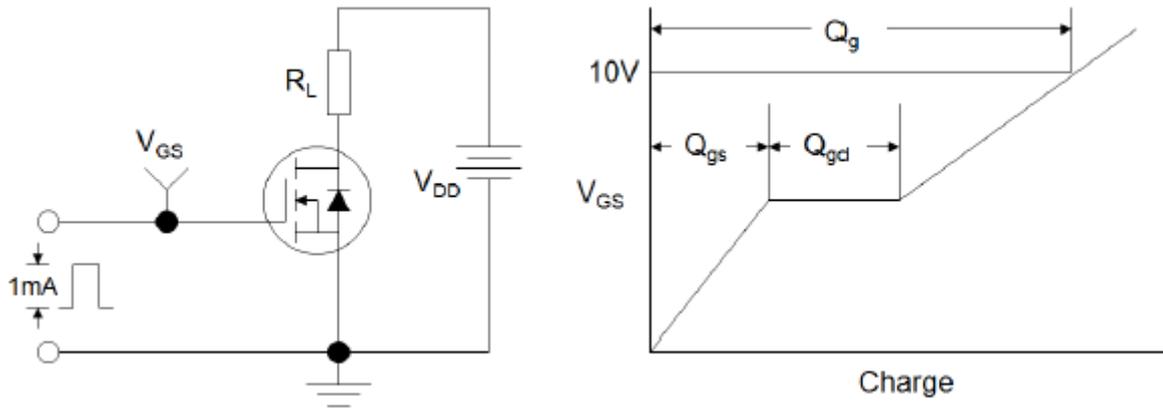


Figure1:Gate Charge Test Circuit & Waveform

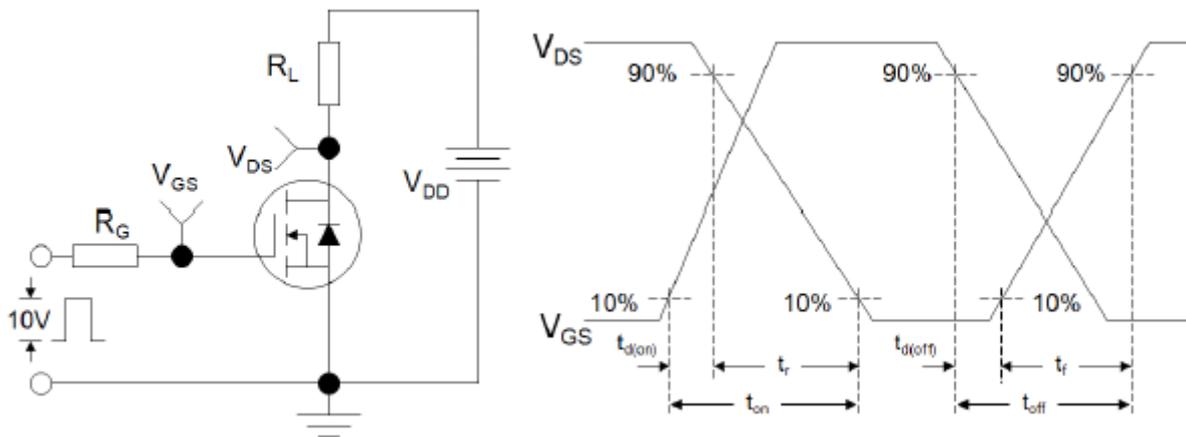


Figure 2: Resistive Switching Test Circuit & Waveforms

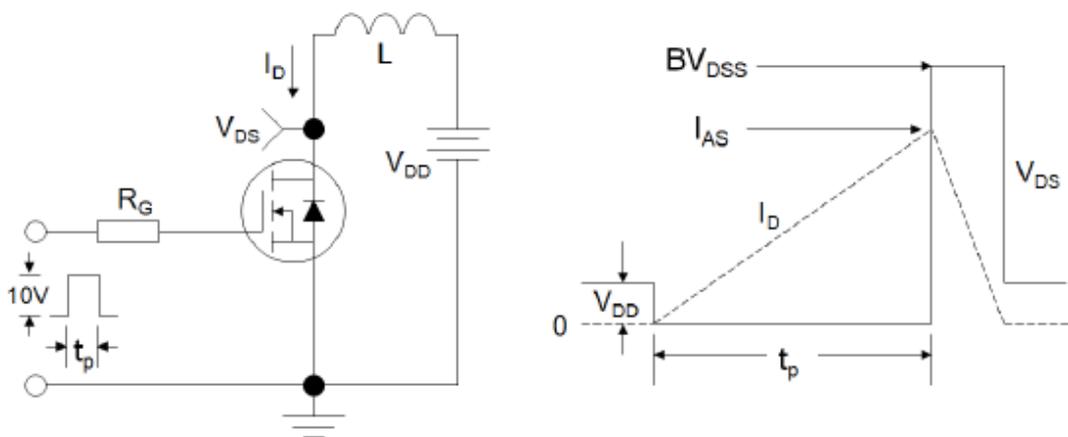


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

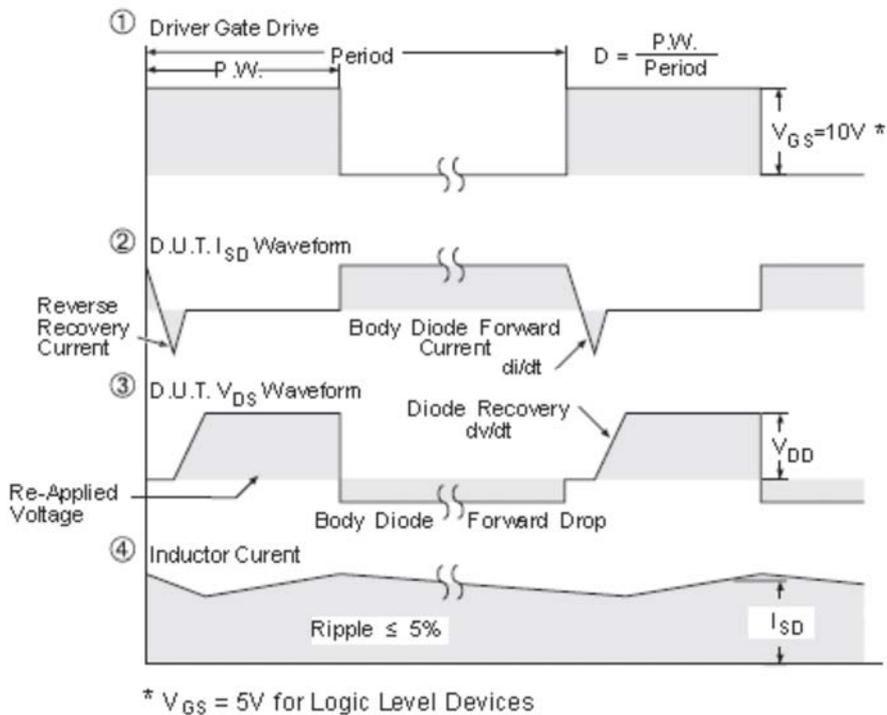
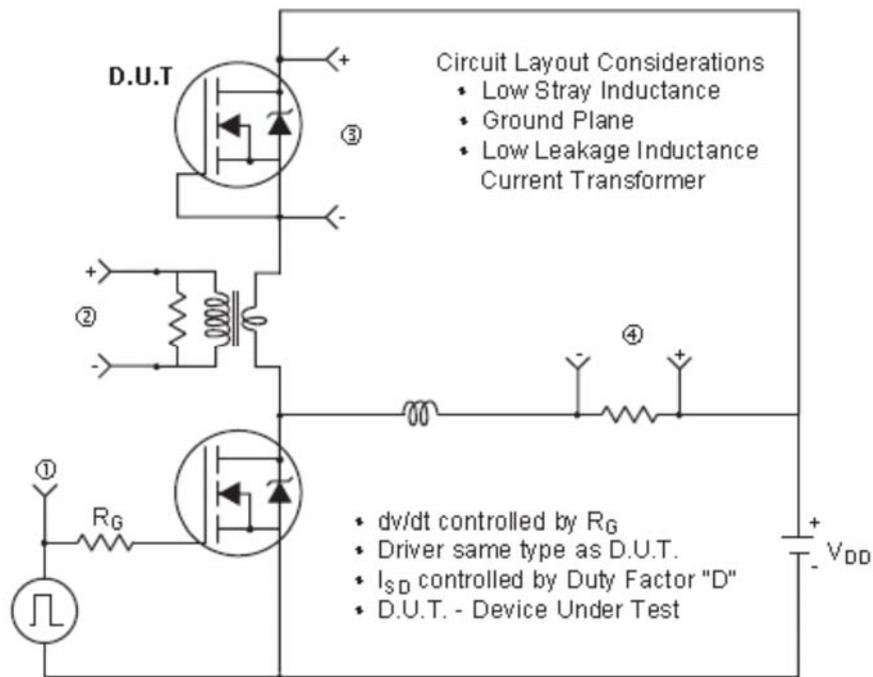
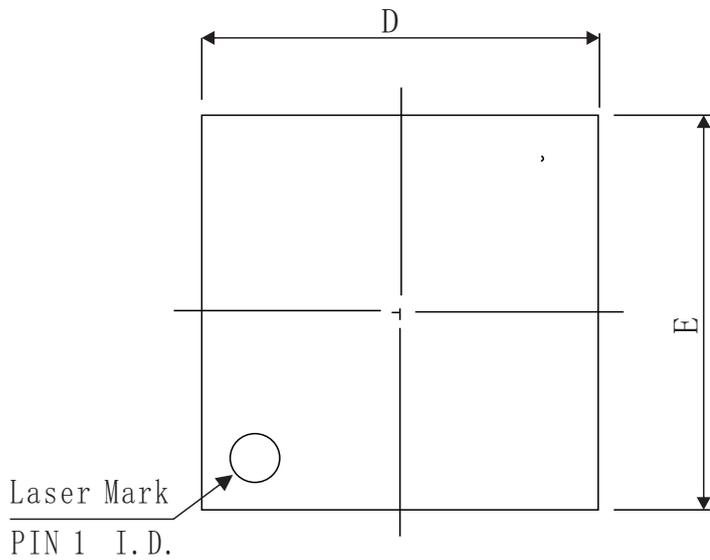
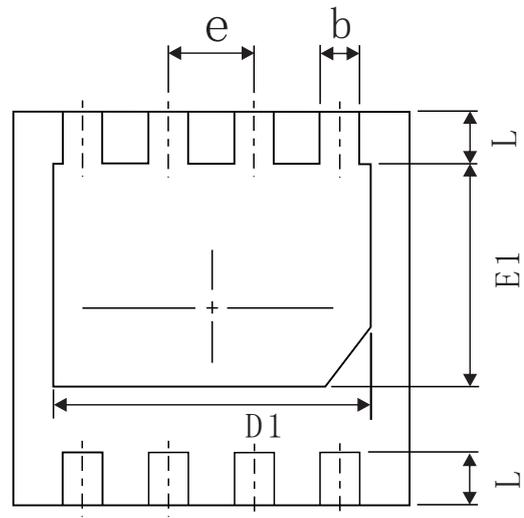


Figure 4: Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)

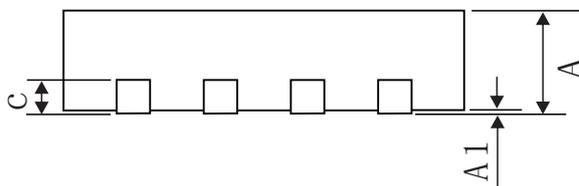
**DFN3\*3-8L Package information**



TOP VIEW



BOTTOM VIEW



SIDE VIEW

COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.25	0.30	0.35
c	0.18	0.20	0.30
D	2.95	3.00	3.07
E	2.95	3.00	3.07
D1	2.30	2.40	2.50
E1	1.60	1.70	1.80
L	0.30	0.40	0.50
e	0.65BSC		